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Kind regards,

Team Nexperia

PESD3V3U1UA; PESD3V3U1UB; PESD3V3U1UL

Ultra low capacitance unidirectional ESD protection diodes

Rev. 01 — 30 October 2008

Product data sheet

1. Product profile

1.1 General description

Ultra low capacitance unidirectional ElectroStatic Discharge (ESD) protection diodes in small Surface-Mounted Device (SMD) plastic packages designed to protect one signal line from the damage caused by ESD and other transients.

Table 1. Product overview

| Type number | Package | | Package configuration |
|-------------|---------|-------|---------------------------|
| | NXP | JEITA | |
| PESD3V3U1UA | SOD323 | SC-76 | very small |
| PESD3V3U1UB | SOD523 | SC-79 | ultra small and flat lead |
| PESD3V3U1UL | SOD882 | - | leadless ultra small |

1.2 Features

- Unidirectional ESD protection of one line
- ESD protection up to 9 kV
- Ultra low diode capacitance: $C_d = 2.6$ pF
- IEC 61000-4-2; level 4 (ESD)
- Very low leakage current: $I_{RM} = 1$ nA
- AEC-Q101 qualified

1.3 Applications

- USB interfaces
- Cellular handsets and accessories
- 10/100/1000 Mbit/s Ethernet
- Portable electronics
- FireWire
- Communication systems
- High-speed data lines
- Computers and peripherals
- Subscriber Identity Module (SIM) card protection
- Audio and video equipment

1.4 Quick reference data

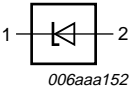
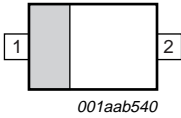
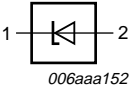
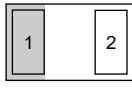
Table 2. Quick reference data

$T_{amb} = 25^\circ\text{C}$ unless otherwise specified.

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-----------|--------------------------|--------------------------|-----|-----|-----|------|
| V_{RWM} | reverse standoff voltage | | - | - | 3.3 | V |
| C_d | diode capacitance | $f = 1$ MHz; $V_R = 0$ V | - | 2.6 | 3.1 | pF |

2. Pinning information

Table 3. Pinning

| Pin | Description | Simplified outline | Graphic symbol |
|---------------------------------|-------------|--|---|
| PESD3V3U1UA; PESD3V3U1UB | | | |
| 1 | cathode | [1] |  |
| 2 | anode |  | |
| PESD3V3U1UL | | | |
| 1 | cathode | [1] |  |
| 2 | anode |  Transparent top view | |

[1] The marking bar indicates the cathode.

3. Ordering information

Table 4. Ordering information

| Type number | Package | | |
|-------------|---------|--|---------|
| | Name | Description | Version |
| PESD3V3U1UA | SC-76 | plastic surface-mounted package; 2 leads | SOD323 |
| PESD3V3U1UB | SC-79 | plastic surface-mounted package; 2 leads | SOD523 |
| PESD3V3U1UL | - | leadless ultra small plastic package; 2 terminals; body 1.0 × 0.6 × 0.5 mm | SOD882 |

4. Marking

Table 5. Marking codes

| Type number | Marking code |
|-------------|--------------|
| PESD3V3U1UA | QT |
| PESD3V3U1UB | T8 |
| PESD3V3U1UL | XZ |

5. Limiting values

Table 6. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | Min | Max | Unit |
|-----------|----------------------|------------|-----|------|------|
| T_j | junction temperature | | - | 150 | °C |
| T_{amb} | ambient temperature | | -55 | +150 | °C |
| T_{stg} | storage temperature | | -65 | +150 | °C |

Table 7. ESD maximum ratings

$T_{amb} = 25\text{ °C}$ unless otherwise specified.

| Symbol | Parameter | Conditions | Min | Max | Unit |
|-----------|---------------------------------|--------------------------------------|-----|-----|------|
| V_{ESD} | electrostatic discharge voltage | IEC 61000-4-2 (contact discharge) | [1] | - | 9 kV |
| | | MIL-STD-883 (human body model) | - | 10 | kV |

[1] Device stressed with ten non-repetitive ESD pulses.

Table 8. ESD standards compliance

| Standard | Conditions |
|---|------------------|
| IEC 61000-4-2; level 4 (ESD) | > 8 kV (contact) |
| MIL-STD-883; class 3 (human body model) | > 4 kV |

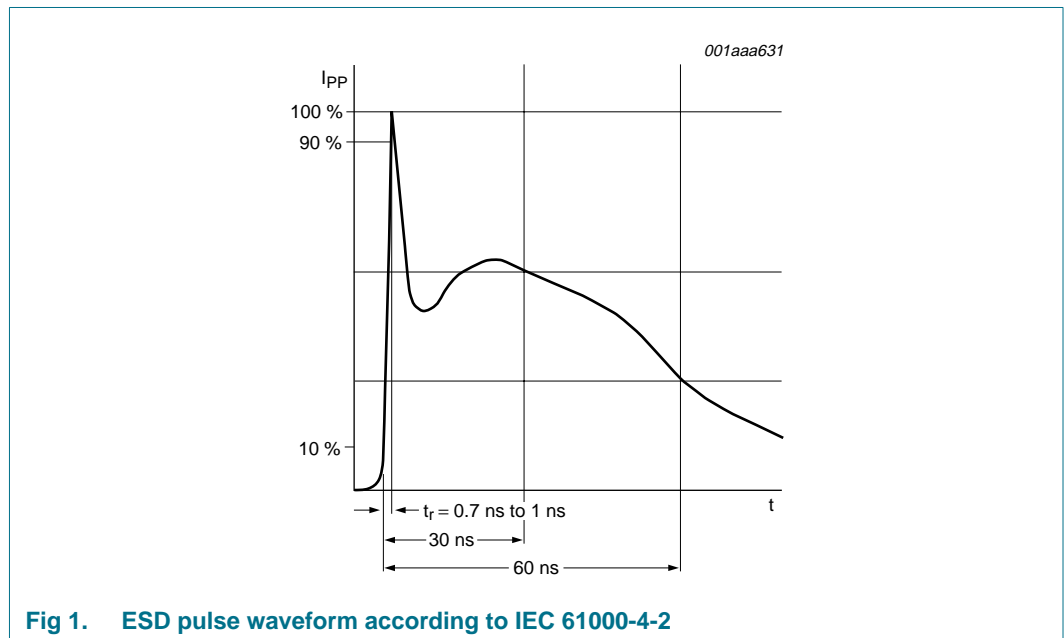


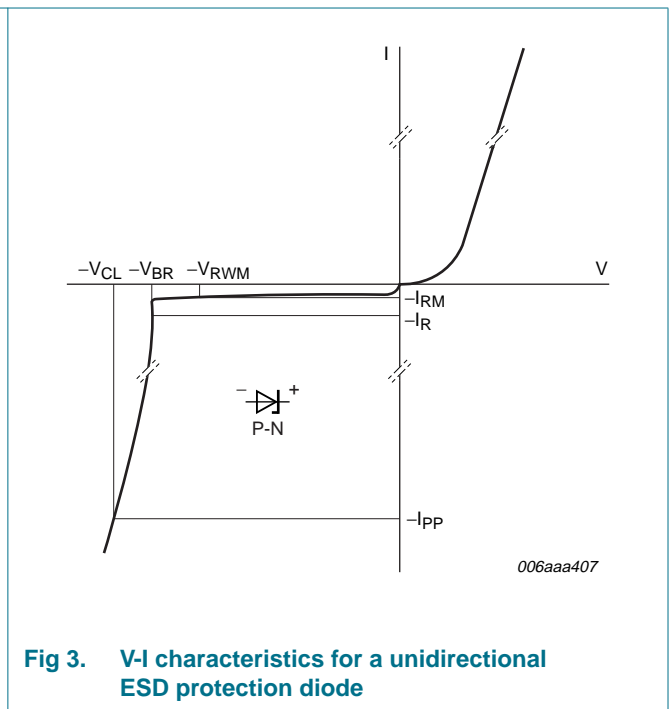
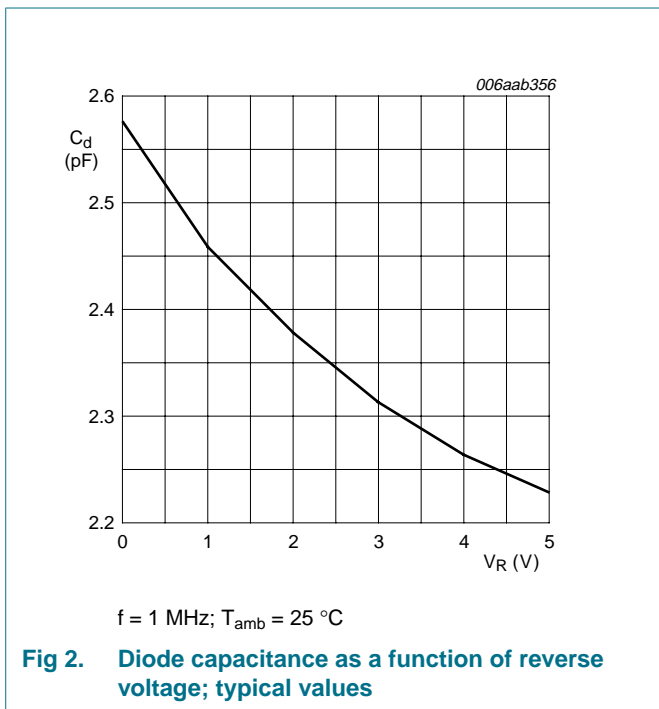
Fig 1. ESD pulse waveform according to IEC 61000-4-2

6. Characteristics

Table 9. Characteristics

T_{amb} = 25 °C unless otherwise specified.

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|------------------|--------------------------|---------------------------------|-----|-----|-----|------|
| V _{RWM} | reverse standoff voltage | | - | - | 3.3 | V |
| I _{RM} | reverse leakage current | V _{RWM} = 3 V | - | 1 | 100 | nA |
| V _{BR} | breakdown voltage | I _R = 5 mA | 4.5 | 5.6 | 6.8 | V |
| C _d | diode capacitance | f = 1 MHz; V _R = 0 V | - | 2.6 | 3.1 | pF |
| r _{dif} | differential resistance | I _R = 5 mA | - | - | 100 | Ω |



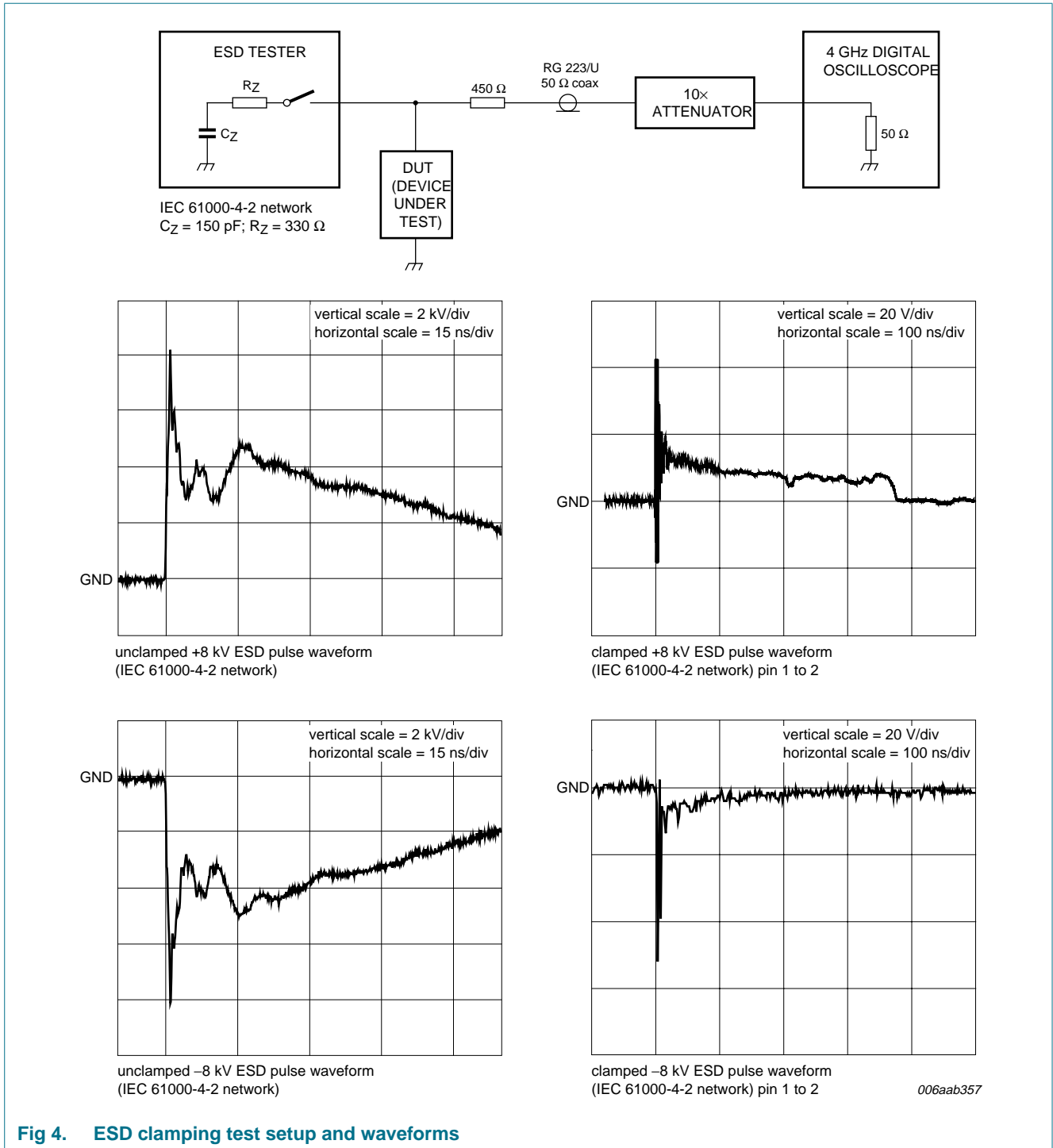


Fig 4. ESD clamping test setup and waveforms

7. Application information

The PESD3V3U1Ux series is designed for the protection of one unidirectional data or signal line from the damage caused by ESD. The devices may be used on lines where the signal polarities are either positive or negative with respect to ground.

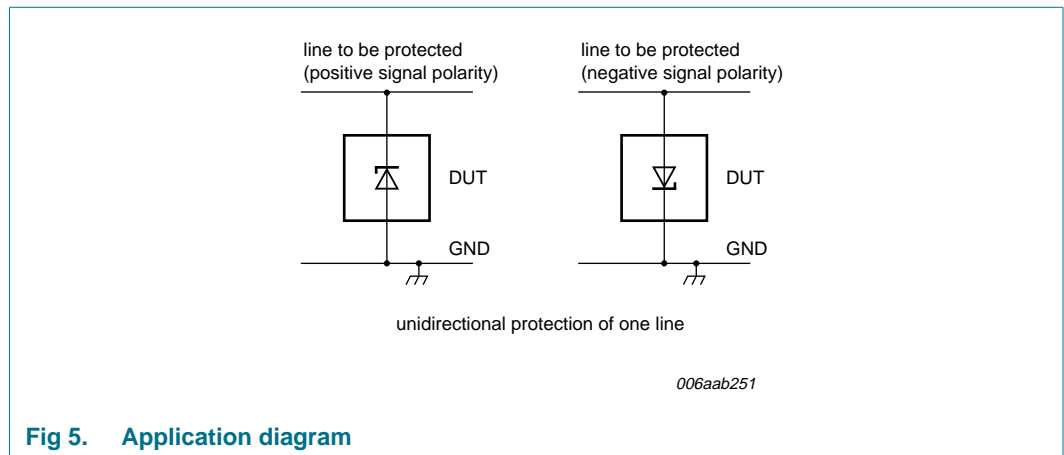


Fig 5. Application diagram

Circuit board layout and protection device placement

Circuit board layout is critical for the suppression of ESD and Electrical Fast Transient (EFT). The following guidelines are recommended:

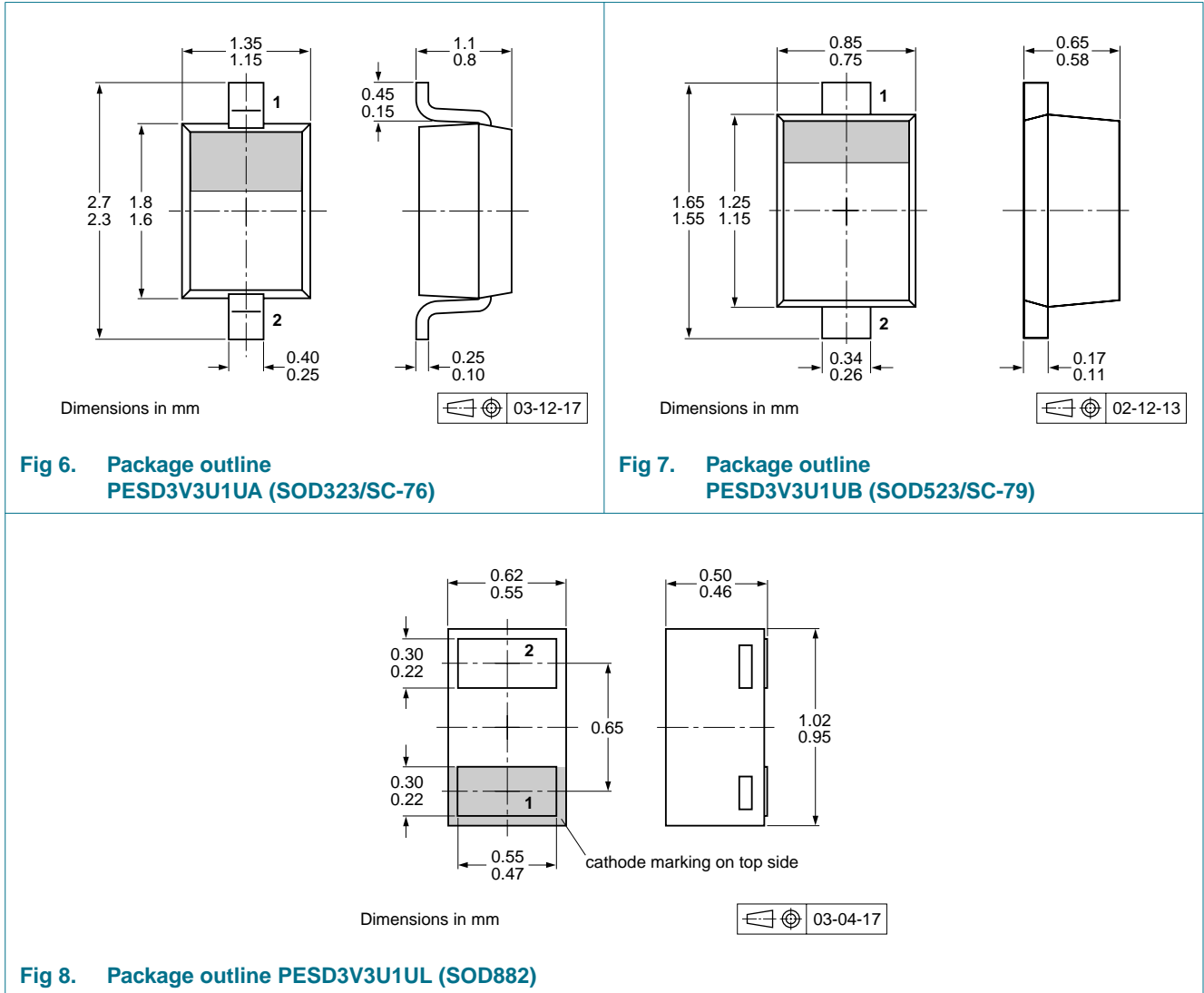
1. Place the device as close to the input terminal or connector as possible.
2. The path length between the device and the protected line should be minimized.
3. Keep parallel signal paths to a minimum.
4. Avoid running protected conductors in parallel with unprotected conductors.
5. Minimize all Printed-Circuit Board (PCB) conductive loops including power and ground loops.
6. Minimize the length of the transient return path to ground.
7. Avoid using shared transient return paths to a common ground point.
8. Ground planes should be used whenever possible. For multilayer PCBs, use ground vias.

8. Test information

8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

9. Package outline



10. Packing information

Table 10. Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code.^[1]

| Type number | Package | Description | Packing quantity | | |
|-------------|---------|--------------------------------|------------------|------|-------|
| | | | 3000 | 8000 | 10000 |
| PESD3V3U1UA | SOD323 | 4 mm pitch, 8 mm tape and reel | -115 | - | -135 |
| PESD3V3U1UB | SOD523 | 2 mm pitch, 8 mm tape and reel | - | -315 | - |
| | | 4 mm pitch, 8 mm tape and reel | -115 | - | -135 |
| PESD3V3U1UL | SOD882 | 2 mm pitch, 8 mm tape and reel | - | - | -315 |

[1] For further information and the availability of packing methods, see [Section 14](#).

11. Soldering

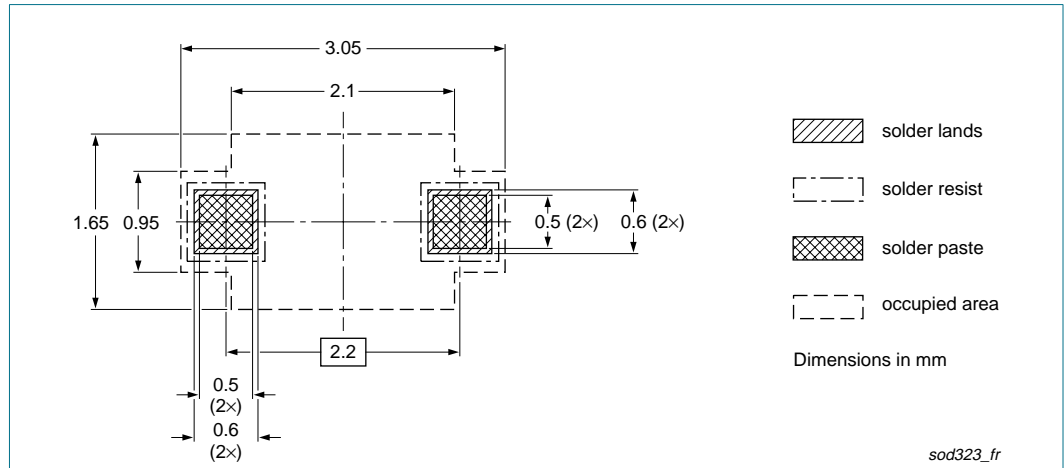


Fig 9. Reflow soldering footprint PESD3V3U1UA (SOD323/SC-76)

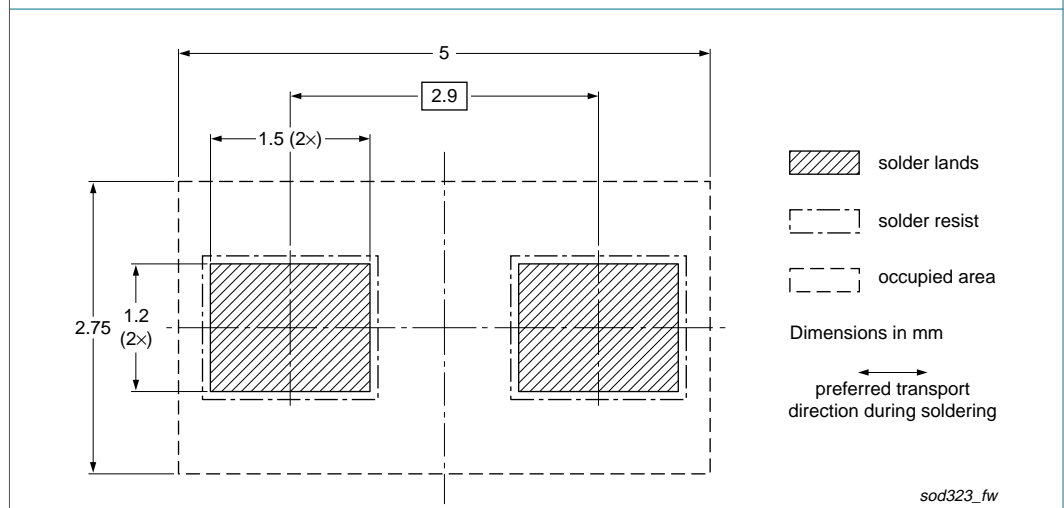
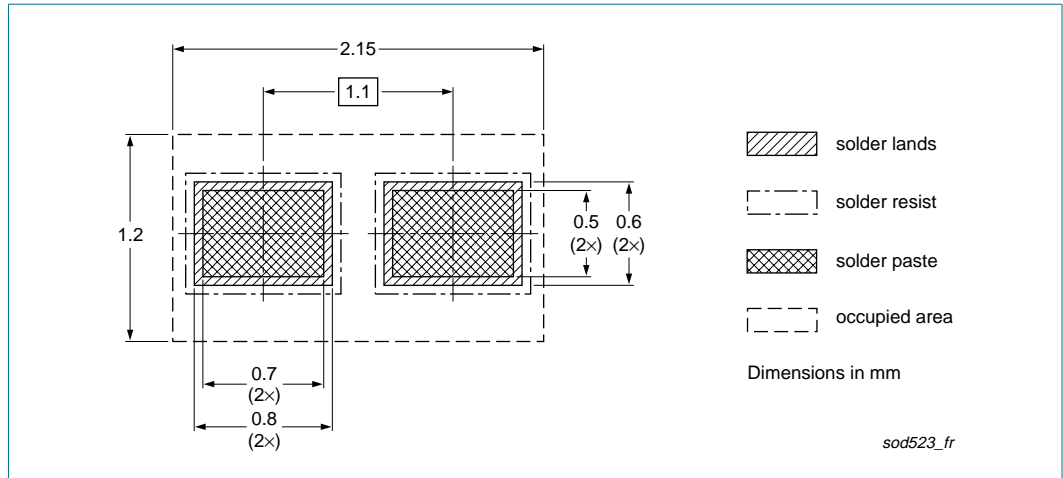
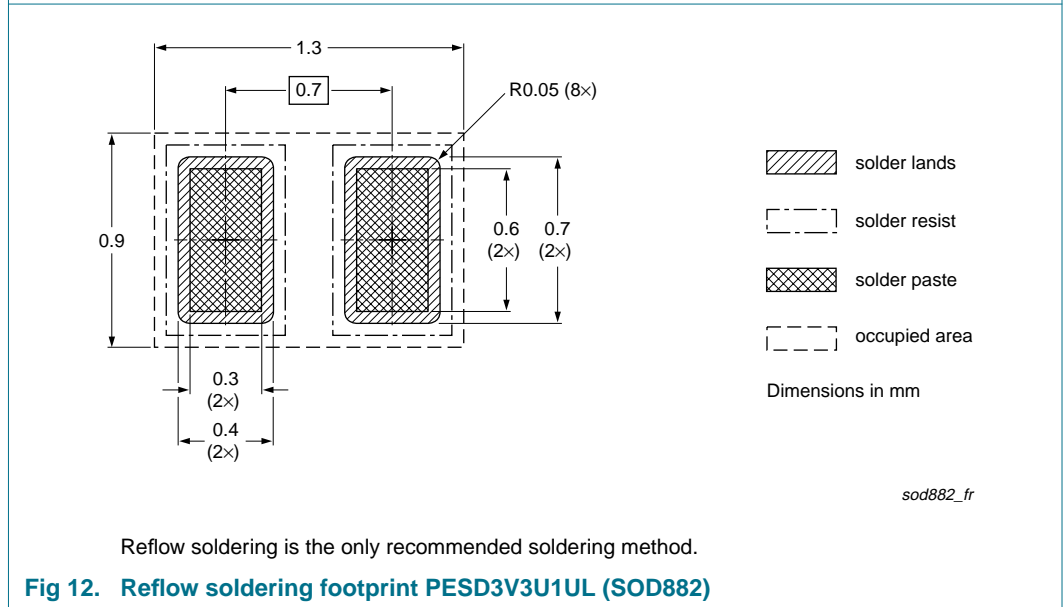


Fig 10. Wave soldering footprint PESD3V3U1UA (SOD323/SC-76)



Reflow soldering is the only recommended soldering method.

Fig 11. Reflow soldering footprint PESD3V3U1UB (SOD523/SC-79)



Reflow soldering is the only recommended soldering method.

Fig 12. Reflow soldering footprint PESD3V3U1UL (SOD882)

12. Revision history

Table 11. Revision history

| Document ID | Release date | Data sheet status | Change notice | Supersedes |
|---------------------|--------------|--------------------|---------------|------------|
| PESD3V3U1UA_UB_UL_1 | 20081030 | Product data sheet | - | - |

13. Legal information

13.1 Data sheet status

| Document status ^{[1][2]} | Product status ^[3] | Definition |
|-----------------------------------|-------------------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
| Product [short] data sheet | Production | This document contains the product specification. |

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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